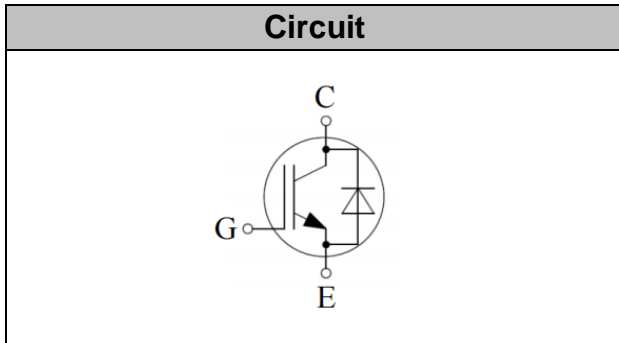


## IGBT Discrete

$V_{CE}$	<b>650</b>	<b>V</b>
$I_C$	<b>10</b>	<b>A</b>
$V_{CE(SAT)} I_C=10A$	<b>1.40</b>	<b>V</b>



### Applications

- Soft switching applications
- Air conditioning
- Motor drive inverter

### Features

- High speed smooth switching device for hard & soft switching
- Maximum junction temperature 175°C
- Positive temperature coefficient
- High ruggedness, temperature stable

## Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-Emitter Breakdown Voltage	$V_{CE}$	650	V
DC Collector Current, limited by $T_{jmax}$ $T_C=25^\circ C$ $T_C=100^\circ C$	$I_C$	20 10	A
Diode Forward Current, limited by $T_{jmax}$ $T_C=25^\circ C$ $T_C=100^\circ C$	$I_F$	20 10	A
Continuous Gate-Emitter Voltage	$V_{GE}$	$\pm 20$	V
Transient Gate-Emitter Voltage ( $t_p \leq 10\mu s, D < 0.010$ )	$V_{GE}$	$\pm 30$	V
Turn off Safe Operating Area $V_{CE} \leq 600V$ , $T_j \leq 150^\circ C$		40	A
Pulsed Collector Current, $V_{GE}=15V$ , $t_p$ limited by $T_{jmax}$	$I_{CM}$	40	A
Short Circuit Withstand Time, $V_{GE}=15V$ , $V_{CE} \leq 400V$	$T_{SC}$	5	$\mu s$
Diode Pulsed Current, $t_p$ limited by $T_{jmax}$	$I_{Fpuls}$	40	A
Power Dissipation, $T_j=175^\circ C, T_c=25^\circ C$	$P_{tot}$	100	W



Operating Junction Temperature	$T_j$	-40...+175	°C
Storage Temperature	$T_s$	-55...+150	°C
Soldering Temperature, wave soldering 1.6mm (0.063in.) from case for 10s		260	°C

### Electrical Characteristics of the IGBT ( $T_j=25^\circ\text{C}$ unless otherwise specified):

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Collector-Emitter Breakdown Voltage	$BV_{CES}$	$V_{GE}=0V, I_C=250\mu A$	650		-	V
Gate Threshold Voltage	$V_{GE(th)}$	$V_{GE}=V_{CE}, I_C=1mA$	4.4	5.2	6.0	V
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$V_{GE}=15V, I_C=10A$ $T_j=25^\circ\text{C}$ , $T_j=125^\circ\text{C}$ $T_j=150^\circ\text{C}$		1.40 1.55 1.60	1.70	V
Zero Gate Voltage Collector Current	$I_{CES}$	$V_{CE}=650V, V_{GE}=0V$ $T_j=25^\circ\text{C}$ , $T_j=150^\circ\text{C}$			0.25 1.00	mA
Gate-Emitter Leakage Current	$I_{GES}$	$V_{CE}=0V, V_{GE}=\pm 20V$			$\pm 200$	nA

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Dynamic</b>						
Input Capacitance	$C_{ies}$	$V_{CE}=25V, V_{GE}=0V,$ $f=1\text{MHz}$	-	0.89	-	nF
Output capacitance	$C_{oes}$		-	0.04	-	
Reverse Transfer Capacitance	$C_{res}$		-	0.01	-	
Gate Charge	$Q_G$	$V_{CC}=300V, I_C=10A,$ $V_{GE}=15V$	-	0.059	-	uC
Short circuit collector current	$I_{C(SC)}$	$V_{GE}=15V, t_{SC}\leq 5\mu s$ $V_{CC}=400V,$ $T_{j,start}=25^\circ\text{C}$	-	110	-	A



**Electrical Characteristics of the Diode** (  $T_j = 25^\circ\text{C}$  unless otherwise specified ):

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Diode Forward Voltage	$V_F$	$I_F = 10\text{A}$ $T_j = 25^\circ\text{C}$ , $T_j = 125^\circ\text{C}$ $T_j = 150^\circ\text{C}$		1.70 1.50 1.40	2.20	V

**Switching Characteristic, Inductive Load**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Dynamic , at <math>T_j = 25^\circ\text{C}</math></b>						
Turn-on Delay Time	$t_{d(on)}$	$T_j = 25^\circ\text{C}$ $V_{CC} = 300\text{V}$ , $I_C = 10\text{A}$ , $V_{GE} = -5\text{V} \sim 15\text{V}$ , $R_g = 51\ \Omega$	-	10	-	ns
Rise Time	$t_r$		-	26	-	ns
Turn-on Energy	$E_{on}$		-	0.36	-	mJ
Turn-off Delay Time	$t_{d(off)}$		-	68	-	ns
Fall Time	$t_f$		-	135	-	ns
Turn-off Energy	$E_{off}$		-	0.17	-	mJ
<b>Dynamic , at <math>T_j = 125^\circ\text{C}</math></b>						
Turn-on Delay Time	$t_{d(on)}$	$T_j = 125^\circ\text{C}$ $V_{CC} = 300\text{V}$ , $I_C = 10\text{A}$ , $V_{GE} = -5\text{V} \sim 15\text{V}$ , $R_g = 51\ \Omega$	-	14	-	ns
Rise Time	$t_r$		-	35	-	ns
Turn-on Energy	$E_{on}$		-	0.42	-	mJ
Turn-off Delay Time	$t_{d(off)}$		-	68	-	ns
Fall Time	$t_f$		-	162	-	ns
Turn-off Energy	$E_{off}$		-	0.29	-	mJ
<b>Dynamic , at <math>T_j = 150^\circ\text{C}</math></b>						
Turn-on Delay Time	$t_{d(on)}$	$T_j = 150^\circ\text{C}$ $V_{CC} = 300\text{V}$ , $I_C = 10\text{A}$ , $V_{GE} = -5\text{V} \sim 15\text{V}$ , $R_g = 51\ \Omega$	-	16	-	ns
Rise Time	$t_r$		-	41	-	ns
Turn-on Energy	$E_{on}$		-	0.46	-	mJ
Turn-off Delay Time	$t_{d(off)}$		-	69	-	ns
Fall Time	$t_f$		-	181	-	ns
Turn-off Energy	$E_{off}$		-	0.33	-	mJ



## Electrical Characteristics of the DIODE

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Dynamic , at T<sub>j</sub>= 25°C</b>						
Reverse Recovery Current	I <sub>rr</sub>	I <sub>F</sub> =10A, V <sub>R</sub> =300V, -di/dt= 365A/μs,	-	6	-	A
Diode reverse recovery time	trr		-	176	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	0.12	-	μC
Reverse Recovery Energy	E <sub>rec</sub>		-	0.05	-	mJ
<b>Dynamic , at T<sub>j</sub>= 125°C</b>						
Reverse Recovery Current	I <sub>rr</sub>	I <sub>F</sub> =10A, V <sub>R</sub> =300V, -di/dt= 365A/μs,	-	7	-	A
Diode reverse recovery time	trr		-	189	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	0.48	-	μC
Reverse Recovery Energy	E <sub>rec</sub>		-	0.09	-	mJ
<b>Dynamic , at T<sub>j</sub>= 150°C</b>						
Reverse Recovery Current	I <sub>rr</sub>	I <sub>F</sub> =10A, V <sub>R</sub> =300V, -di/dt= 365A/μs,	-	8	-	A
Diode reverse recovery time	trr		-	195	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	0.62	-	μC
Reverse Recovery Energy	E <sub>rec</sub>		-	0.11	-	mJ

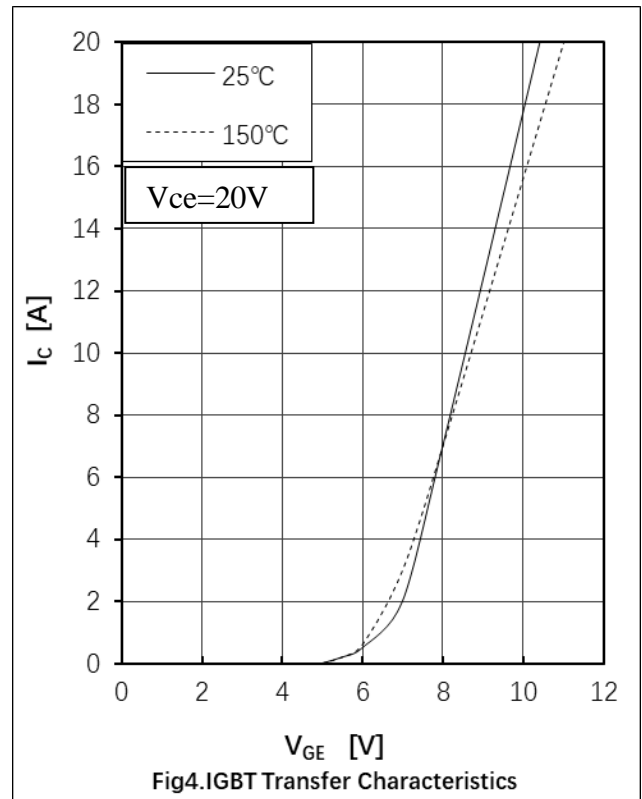
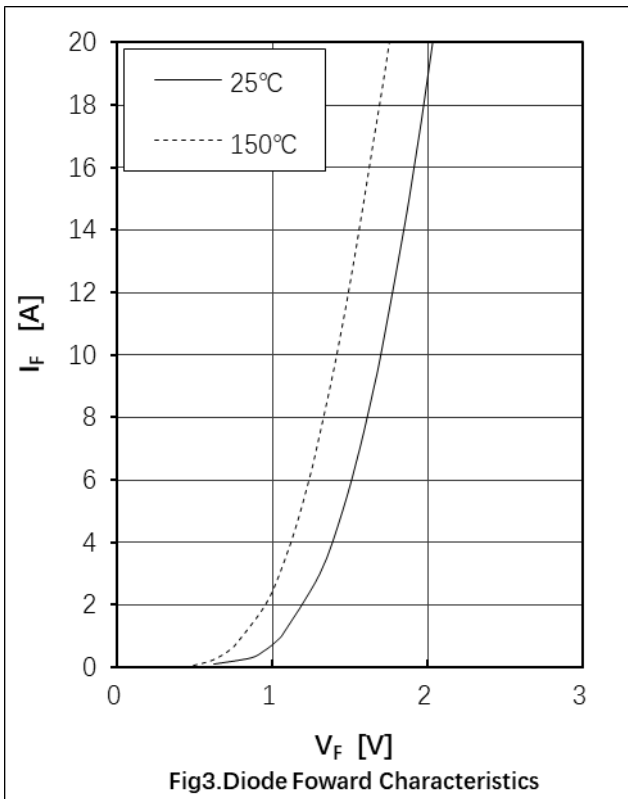
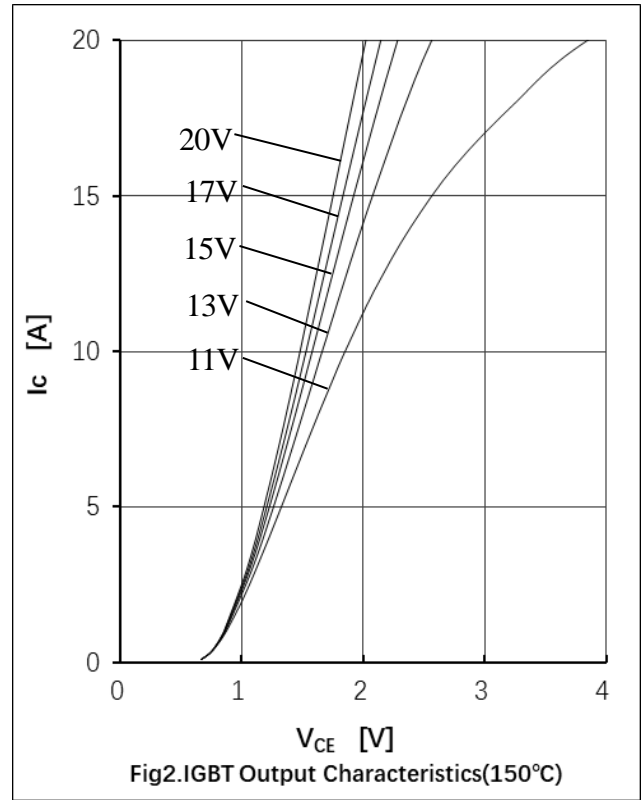
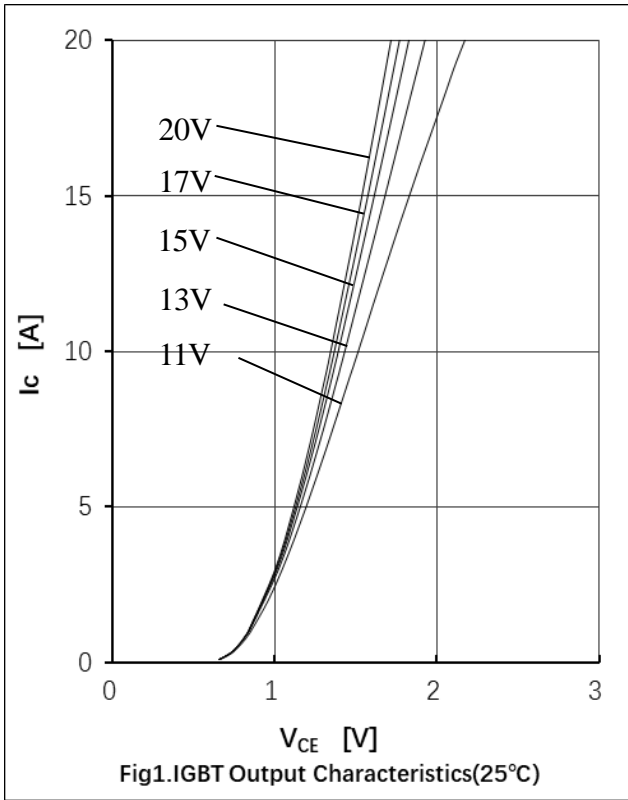
## Thermal Resistance

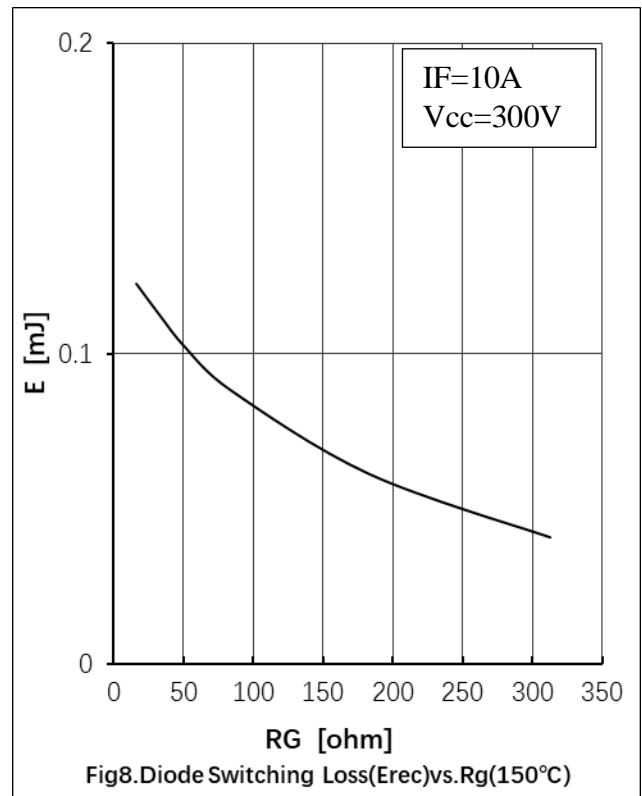
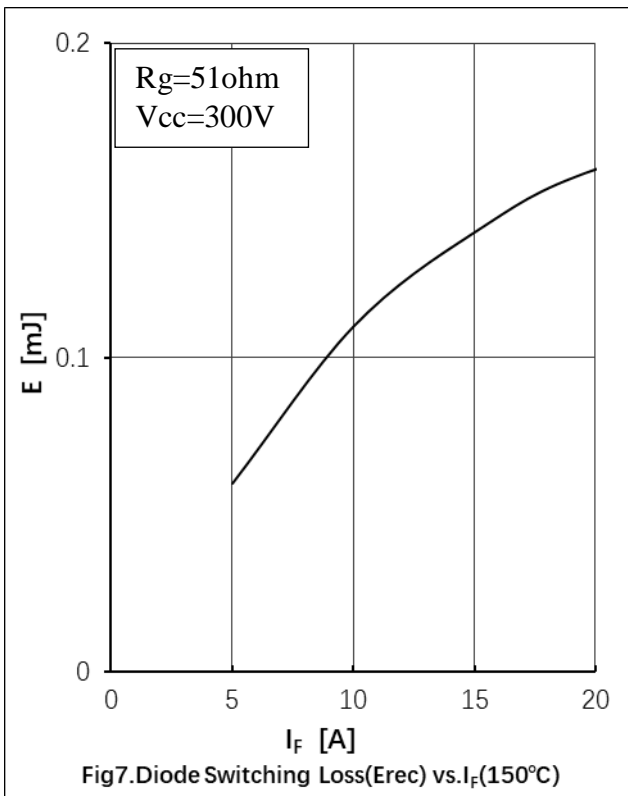
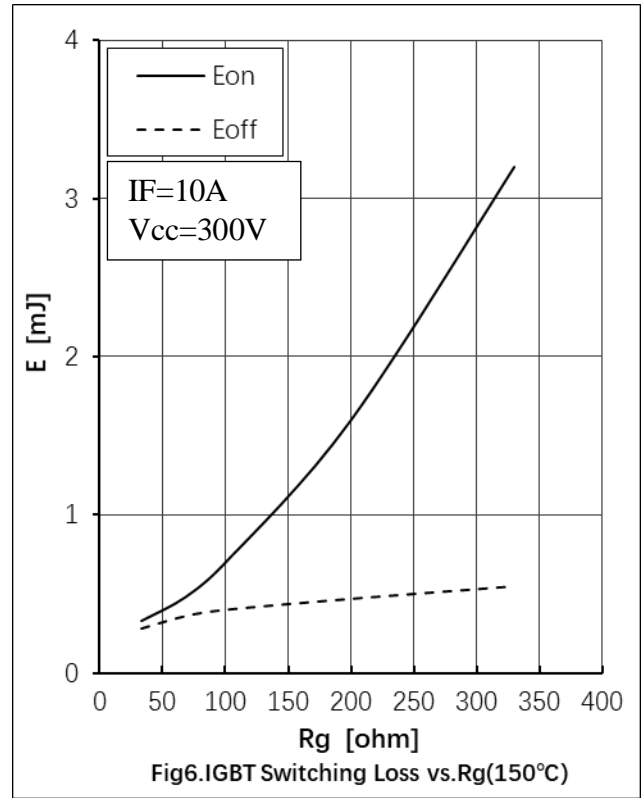
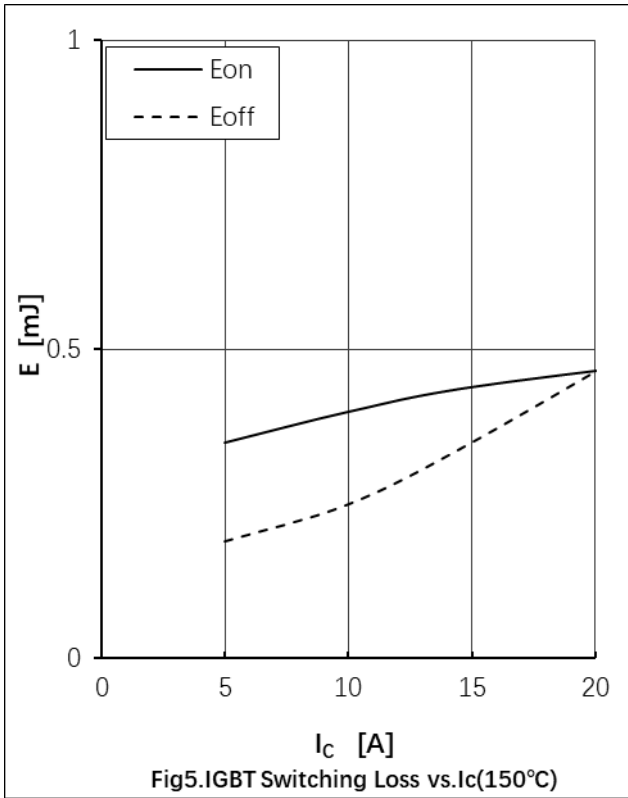
Parameter	Symbol	Max. Value	Unit
IGBT Thermal Resistance, Junction - Case	R <sub>th(j-c)</sub>	1.5	K/W
Diode Thermal Resistance, Junction - Case	R <sub>th(j-c)</sub>	2.0	K/W
Thermal Resistance, Junction - Ambient	R <sub>th(j-a)</sub>	60	K/W

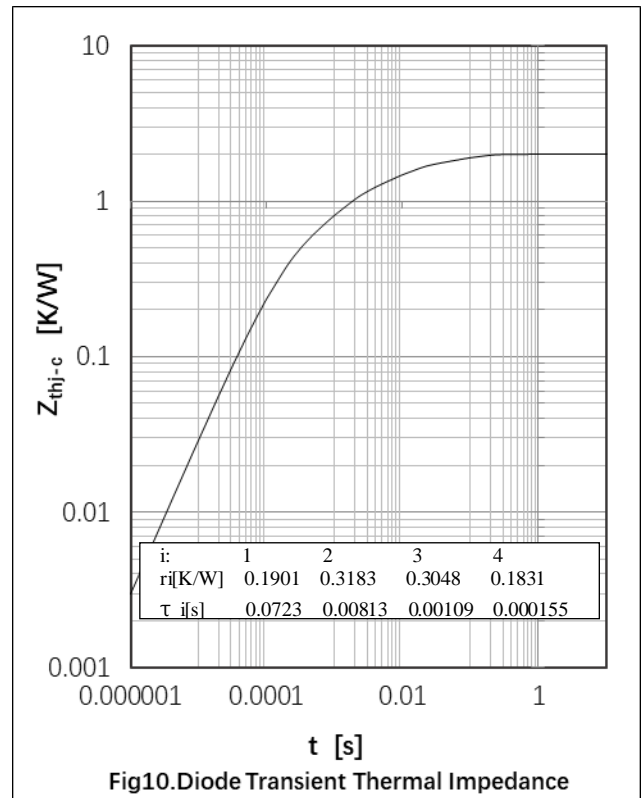
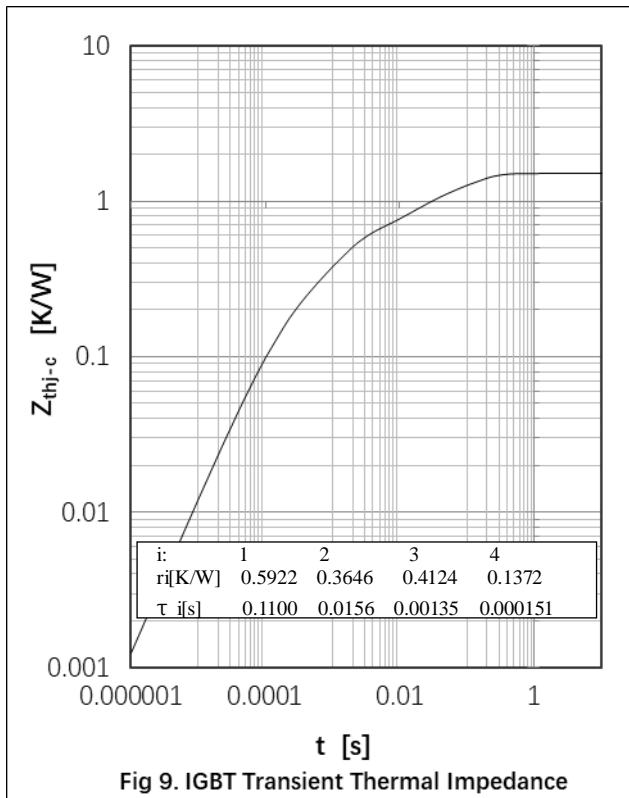


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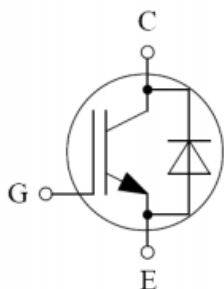
**RoHS**  
COMPLIANT







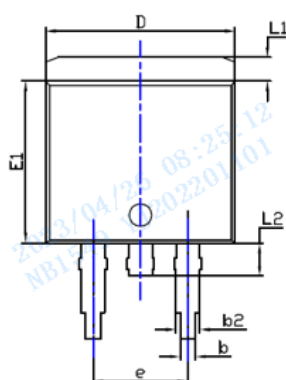
## ● Circuit Diagram



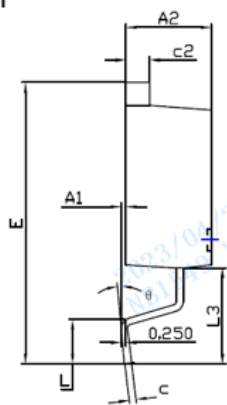
## ● Package Outline Information

CASE: TO 263

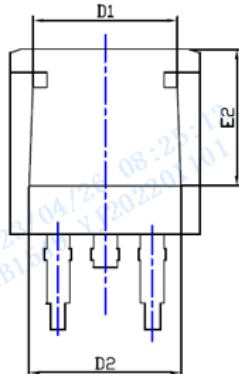
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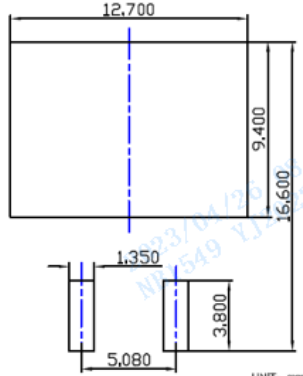
TOP VIEW



SIDE VIEW



BOTTOM VIEW



SUGGESTED SOLDER PAD LAYOUT

UNIT: mm

SYMBOL	DIMENSIONS					
	INCHES			Millimeter		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A1	0,000	---	0,010	0,000	---	0,250
A2	0,174	0,180	0,186	4,430	4,580	4,730
b	0,028	0,032	0,036	0,720	0,820	0,920
b2	0,046	0,050	0,054	1,180	1,280	1,380
c	0,013	0,015	0,018	0,330	0,390	0,450
c2	0,048	0,050	0,053	1,220	1,280	1,34
D	0,394	0,400	0,406	10,000	10,150	10,300
D1	0,295	0,307	0,319	7,500	7,800	8,100
D2	0,303	0,315	0,327	7,700	8,000	8,300
E	0,571	0,591	0,610	14,500	15,000	15,500
E1	0,337	0,341	0,348	8,550	8,700	8,850
E2	0,276	0,287	0,299	7,000	7,300	7,600
e	0,200BSC			5,080BSC		
L	0,070	---	0,110	1,790	---	2,790
L1	0,044	---	0,056	1,120	---	1,420
L2	0,030	---	0,070	0,770	---	1,770
L3	0,197REF			5,000REF		
∅	0*	---	8*	0*	---	8*

### NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.





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